

LL05UT1006

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LL05UT1006

60W Ultra Low Capacitance Uni-Directional TVS For ESD Protection 5.0V

Features

- Protects one I/O line.
- Each I/O pin can withstand over 1000 ESD strikes for $\pm 20\text{kV}$ contact discharge.
- Provide transient protection:
 - IEC 61000-4-2 (ESD) $\pm 25\text{kV}$ (Air), $\pm 20\text{kV}$ (Contact).
 - IEC 61000-4-5 (Lightning) 4A (8/20 μs).
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex.LL05UT1006-H,

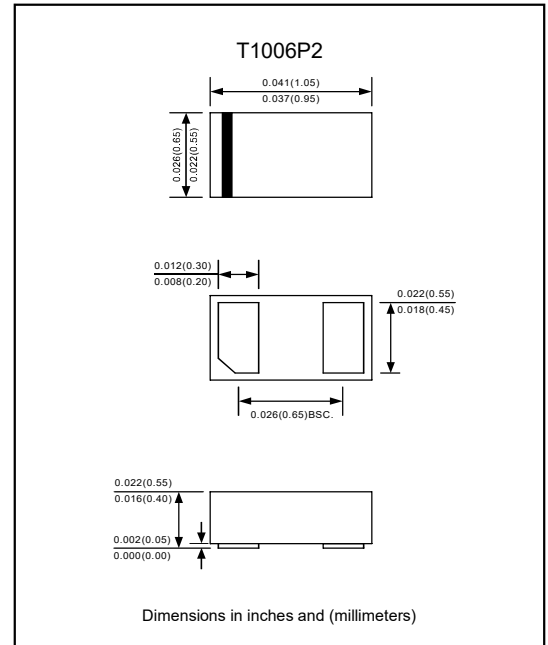
Applications

- Portable applications and communication systems.
- Computers and peripherals.
- High speed data lines: USB 2.0/3.0(Gen1), eSATA and display port.

Mechanical data

- Epoxy: UL94V-0 rated flame retardant.
- Case : Molded plastic, T1006P2.

Package outline



Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power ($t_p=8/20\mu\text{s}$)	P_{PP}	60	W
Peak pulse current ($t_p=8/20\mu\text{s}$)	I_{PP}	4	A
ESD per IEC 61000-4-2 (Contact)	V_{ESD}	± 20	kV
ESD per IEC 61000-4-2 (Air)		± 25	
Operating temperature	T_{OPT}	+125	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

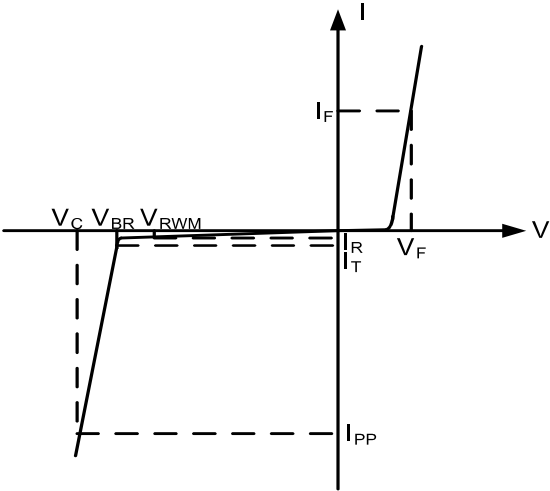
Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Reverse stand-off voltage		V_{RWM}			5	V
Reverse leakage current	$V_{RWM}=5.0\text{V}$, $T=25^\circ\text{C}$	I_R		1	100	nA
Trigger voltage	$I_T=1\text{mA}$	V_{BR}	6	8		V
Clamping voltage	$I_{PP}=4\text{A}$, $t_p=8/20\mu\text{s}$	V_C			15	V
Clamping voltage	$I_{PP}=8\text{A}$, $t_p=100\text{ns}$ (Note1)	V_C		9.6		V
	$I_{PP}=16\text{A}$, $t_p=100\text{ns}$ (Note1)			11.5		
Dynamic resistance	$I_{PP}=12\text{A}$, $t_p=100\text{ns}$ (Note1)	R_{dyn}		0.24		Ω
Junction capacitance	$V_R=0\text{V}$, $f=1.0\text{MHz}$	C_{ESD}		0.65		pF

Note: 1. Measurements performed using a 100ns transmission line pulse(TLP) system.

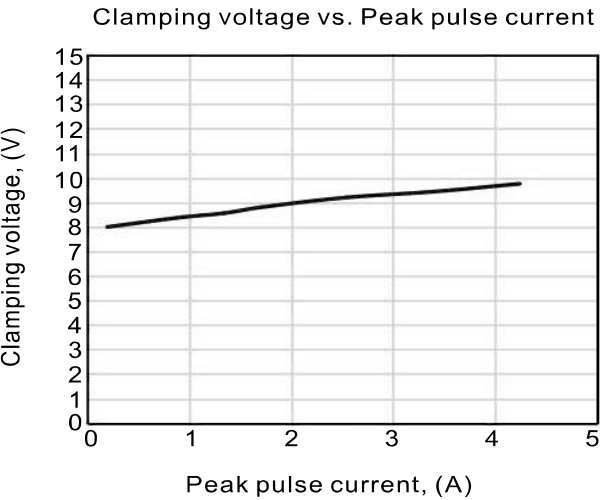
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Rating and characteristic curves

Symbol	Parameter
V_{RWM}	Nominal reverse working voltage
I_R	Reverse leakage current@ V_{RWM}
V_{BR}	Reverse breakdown voltage@ I_T
I_T	Test current for reverse breakdown
V_C	Clamping voltage @ I_{PP}
I_{PP}	Peak pulse current
C_{ESD}	Parasitic capacitance
I_F	Forward current
V_F	Forward voltage @ I_F

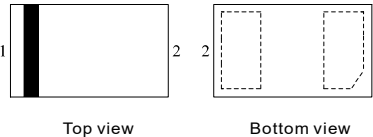
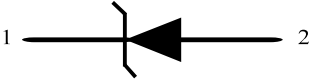


Uni-Directional TVS



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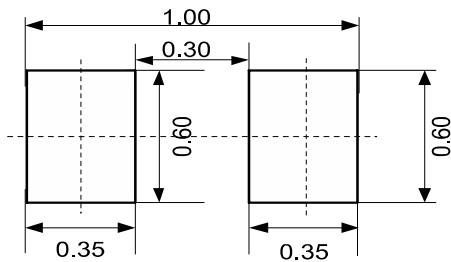
Pinning information

Pin	Simplified outline	Symbol
Pin1 Cathode Pin2 Anode	 Top view Bottom view	

Marking

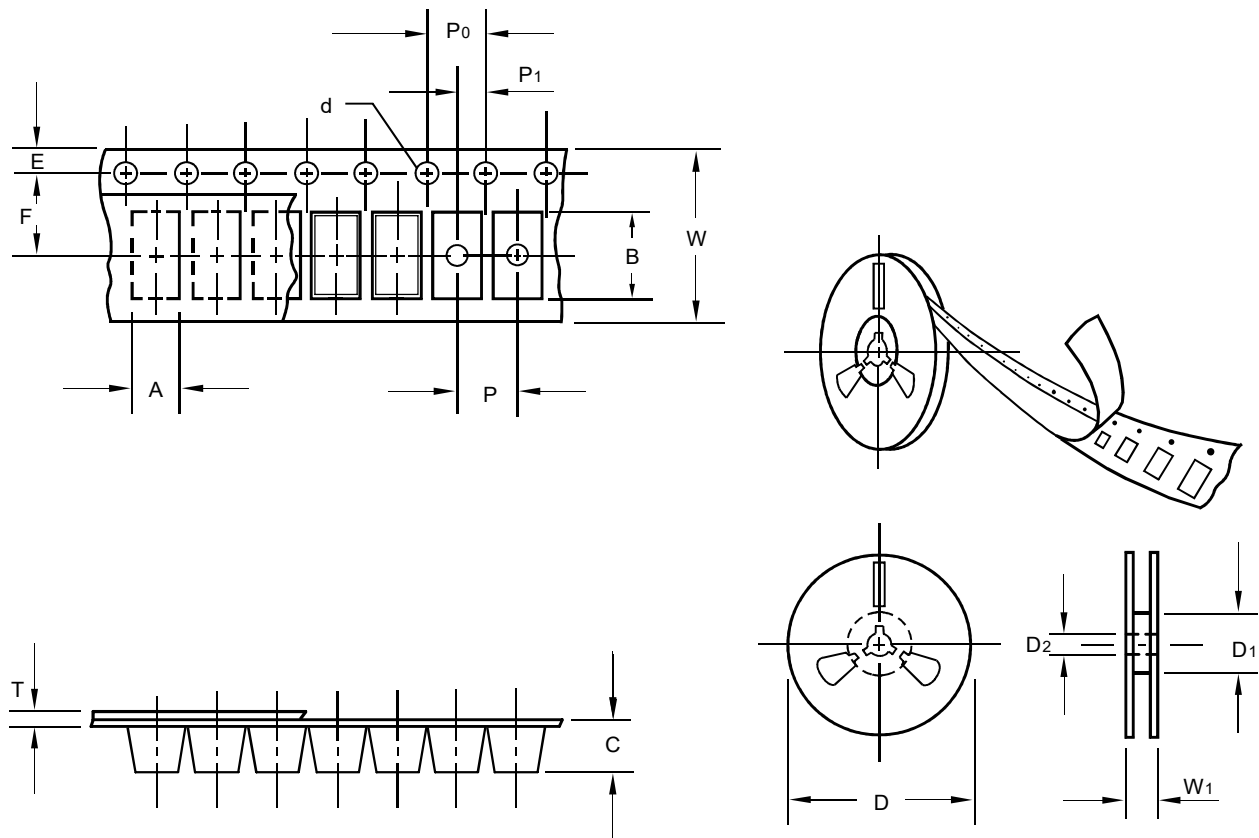
Type number	Marking code
LL05UT1006	TX

Suggested solder pad layout



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Packing information



unit:mm

Item	Symbol	Tolerance	T1006P2
Carrier width	A	0.1	0.70
Carrier length	B	0.1	1.15
Carrier depth	C	0.1	0.55
Sprocket hole	d	0.1	1.55
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	55.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.20
Tape width	W	0.3	8.00
Reel width	W1	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

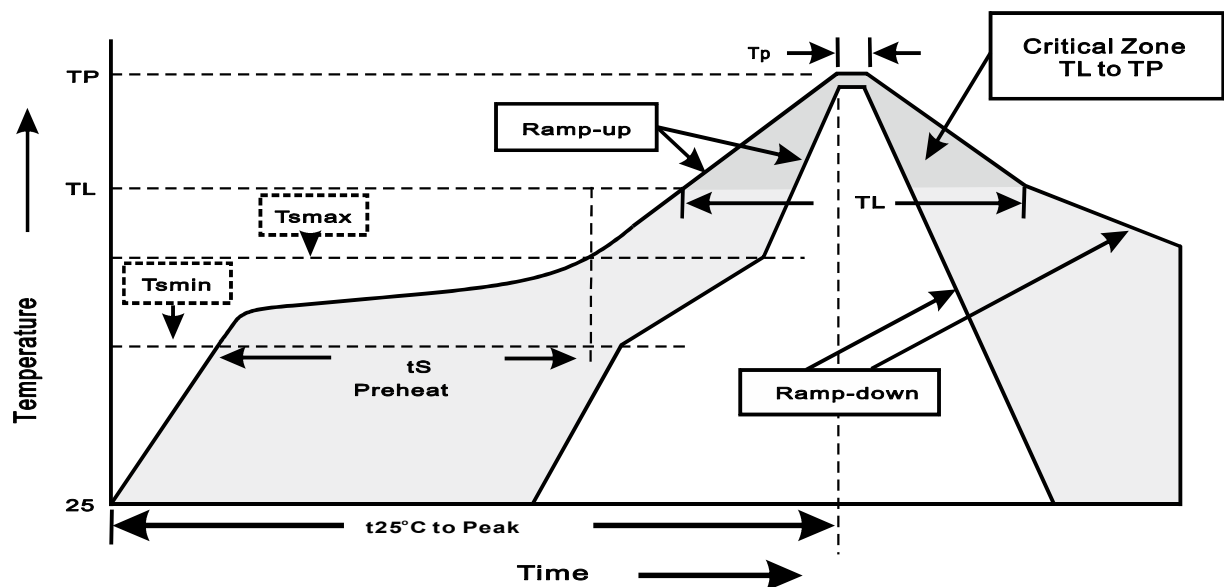
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
T1006P2	7"	10,000	4.0	100,000	183*123*183	178	382*257*387	800,000

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



- 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{Smin}) -Temperature Max(T _{Smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{Smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes